



# Product Change Notification

<b>Date Issued :</b>	March 24, 2023	<b>PCN Number :</b>	513486
<b>Reason for Change :</b>	Manufacturing Process Change (Molex)		
<b>Description of Change :</b>	The purpose of this letter is to change Au plating area to improve production efficiency. It is difficult to maintain the selling price of the current plating by the dipping method, in order to not raise the selling price, Molex analyzed the plating process of terminal and improve the plating area of non-functional.		
<b>Assessment of Change :</b>	Reliability Test Report/s		
<b>Planned Implementation Date :</b>	October 31, 2023		
<b>Sample Availability Date:</b>	August 04, 2023		
<b>Internal Molex Qualification Date :</b>	August 04, 2023		
<b>Last date to request Samples by Customer :</b>	September 21, 2023		
<b>Traceability Code Markings / Date :</b>	Product made after planned implementation date can contain the change		

Before Picture

## Overview

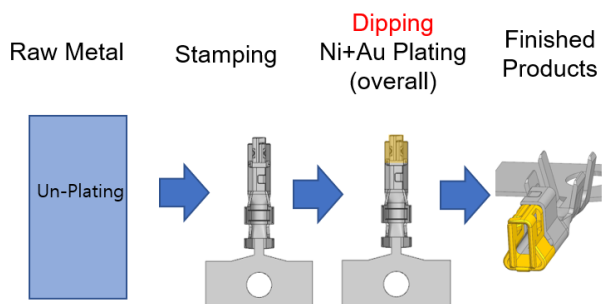
- The purpose of this letter is to change Au plating area to improve production efficiency.
- It is difficult to maintain the selling price of the current plating by the dipping method, in order to not raise the selling price, Molex analyzed the plating process of terminal and improve the plating area of non-functional.
- Part Number Impact
  - Please refer attached impacted part list.
- Qualification Reports and samples available upon request after the date shown above.
- Implementation date may be updated due to customer demand and production condition.

After Picture

### Before

- We are making a manufacturing process on to stamping and plating area for effective Au selective plating.

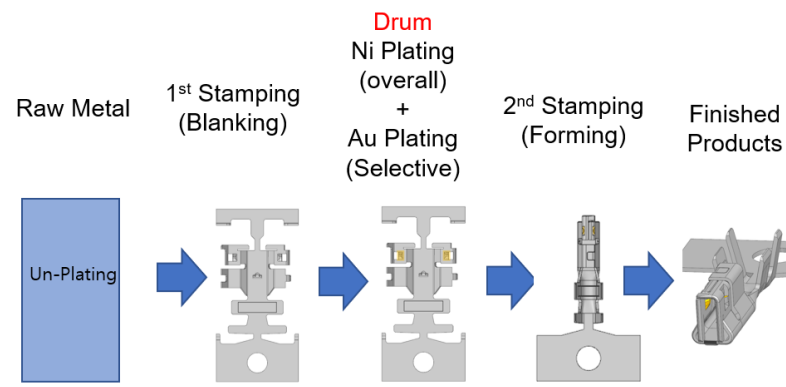
#### Manufacturing process



### After

- Change makes the stable performance by equally Ni plating thickness.
- Definite Au selective plating area will be applied on contact area.

#### Manufacturing process

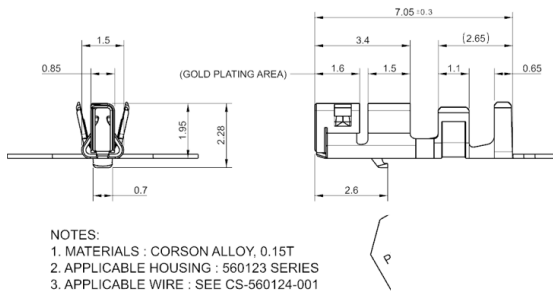


RELEASED

## Additional Information :

**Before**

- We are making a design change on to Au plating area for optimized manufacturing process.
- SD-560124-002

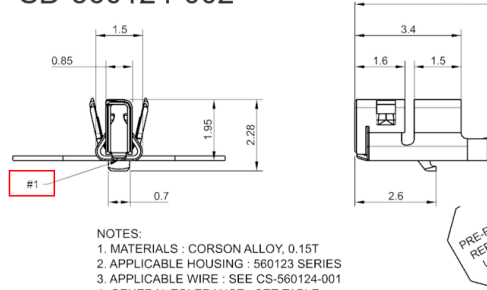


## NOTES:

1. MATERIALS : CORSON ALLOY, 0.15T
2. APPLICABLE HOUSING : 560123 SERIES
3. APPLICABLE WIRE : SEE CS-560124-001
4. GENERAL TOLERANCE : SEE TABLE
5. ELV AND RoHS COMPLIANT
6. PRODUCT SPECIFICATION : PS-5601240131
7. PACKING SPECIFICATION : PK-560124-001
8. CRIMP SPECIFICATION : CS-560124-001
9. PLATING : Au SELECTIVE  
(Ni : 1.5um Min. UNDER PLATING, Au : 0.2um Min.)

**After**

- A change makes the stable performance by equally plating thickness.
- Focusing on Au plating area on contact.
- There will be changes to plating area as the changed SD.
- SD-560124-002



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8. CRIMP SPECIFICATION : CS-560124-001
9. PLATING : (CONTACT AREA) SEPARATED Au PLATING 0.2um Min.  
(UNDERPLATE) NICKEL OVERALL 1.5um Min.  
(UNPLATE) AREA #1

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You may address inquires regarding this PCN by clicking on the below link  
[mailto:pcn\\_coordinator@molex.com?subject=PCN\\_Notification:513486](mailto:pcn_coordinator@molex.com?subject=PCN_Notification:513486)  
 or contact your Local Sales Engineer.

Note: While responding, please retain " PCN Notification : **PCN Notification: 513486** " in the e-mail Subject line for faster response.

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**PCN No Part List**

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